



Advance Product Change Notification

201811044AW

Issue Date: 16-May-2019 **WITHDRAWAL**

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

WITHDRAWAL OF PRE ALERT: SPC5777C, SPC5775B/E Burn-In/ Assembly and Final Test Site Expansions

Description of Change

This is withdrawal notification for the change described below. See the Withdrawal Information section for further details.

Original Description of Change:

NXP Semiconductors announces the following site expansions for the SPC5777C/ B/ E, Mask Set N45H products associated with this notification:

1. Assembly site expansion from the current NXP-ATTJ, Tianjin, China assembly facility to the NXP-ATKL, Kuala Lumpur, Malaysia assembly facility.
2. Burn-in site expansion from the current KESM (Kuala Lumpur), Kuala Lumpur, Malaysia Burn-in site to

the KESM (Tianjin), Tianjin, China Burn-in site.

3. Final test site expansion from the current NXP-ATKL, Kuala Lumpur, Malaysia Final Test site to the NXP-ATTJ, Tianjin, China Final Test site.

For the assembly site expansion, there is no change to the package bill of material (BOM) between the two assembly sites.

Expected qualification of associated sites is April 2019. An update to this notification with qualification results will be issued at that time.

Supplemental information on Prototype Part numbers for sample orders, Key Dates and the part number Nomenclature Decoder for the assembly site expansion are attached.

The above changes coincides with DeQuMa ID: SEM-PA-18 and SEM-TF-01.

Reason for Change

Not applicable

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not applicable

Sample information not applicable.

Production

Planned first shipment 10-May-2019

Withdrawal Information

1. NXP is withdrawing the Pre Alert_201811044A due to realignment of internal priorities.

2. A new product change notification will be distributed for SPC5777C at a later date.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 10-May-2019.

The Final PCN is planned to be issued on: 10-May-2019.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 15-Jun-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Affected Part Numbers

SPC5777CK2MMO3

SPC5777CCK3MME3

SPC5777CK2MME3

SPC5777CK3MMO3

SPC5775BDK3MME2

SPC5777CK3MME3

SPC5777CDK3MME3

SPC5777CDK3MMO3

SPC5775EDK3MME3